

# MECHANICAL CASE OUTLINE

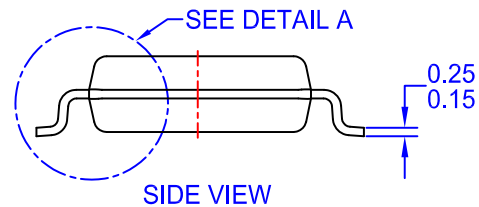
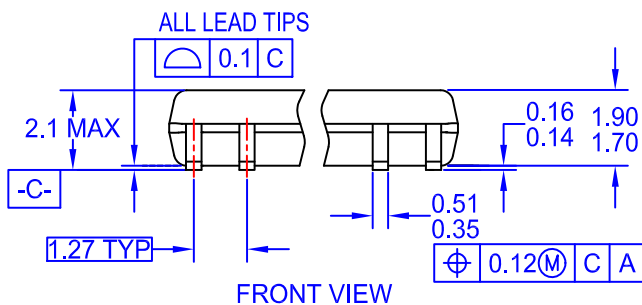
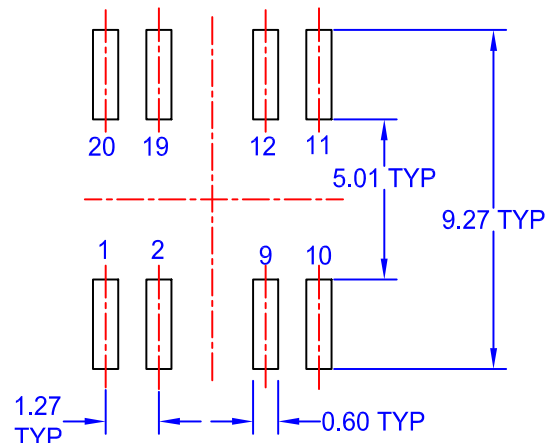
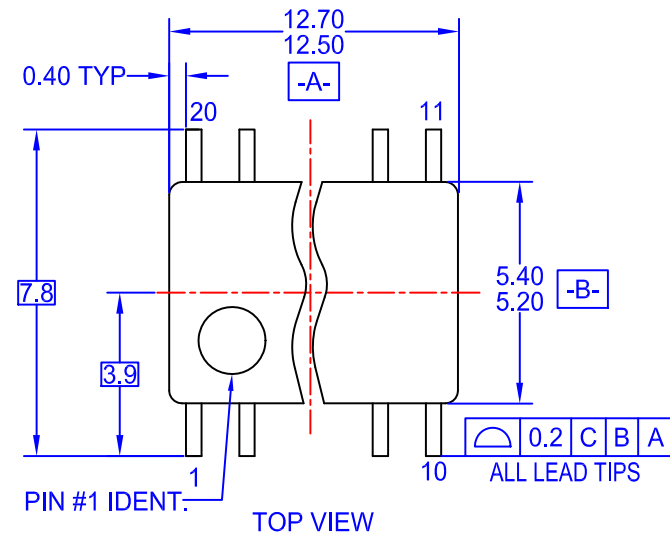
## PACKAGE DIMENSIONS

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SOP20  
CASE 565BG  
ISSUE O


DATE 31 DEC 2016



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